

# Proceso de Fabricación CMOS

Asignatura: Tecnología de  
Computadores

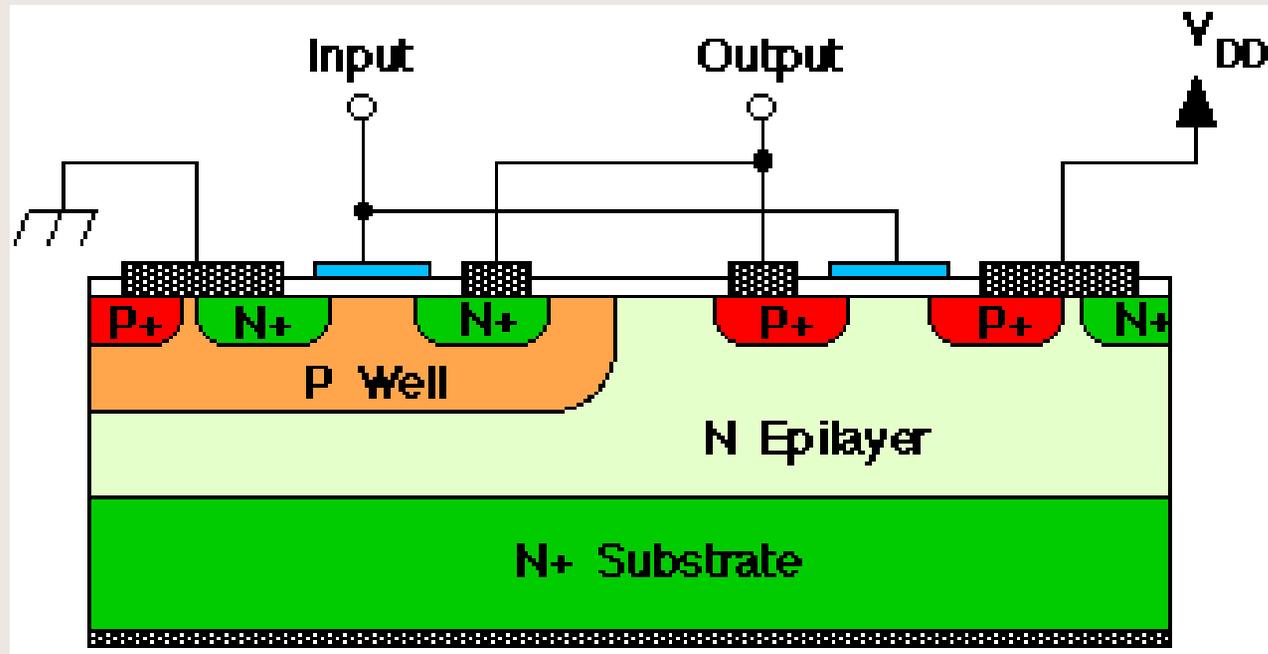
Grupo: 22M

Curso 2004-2005

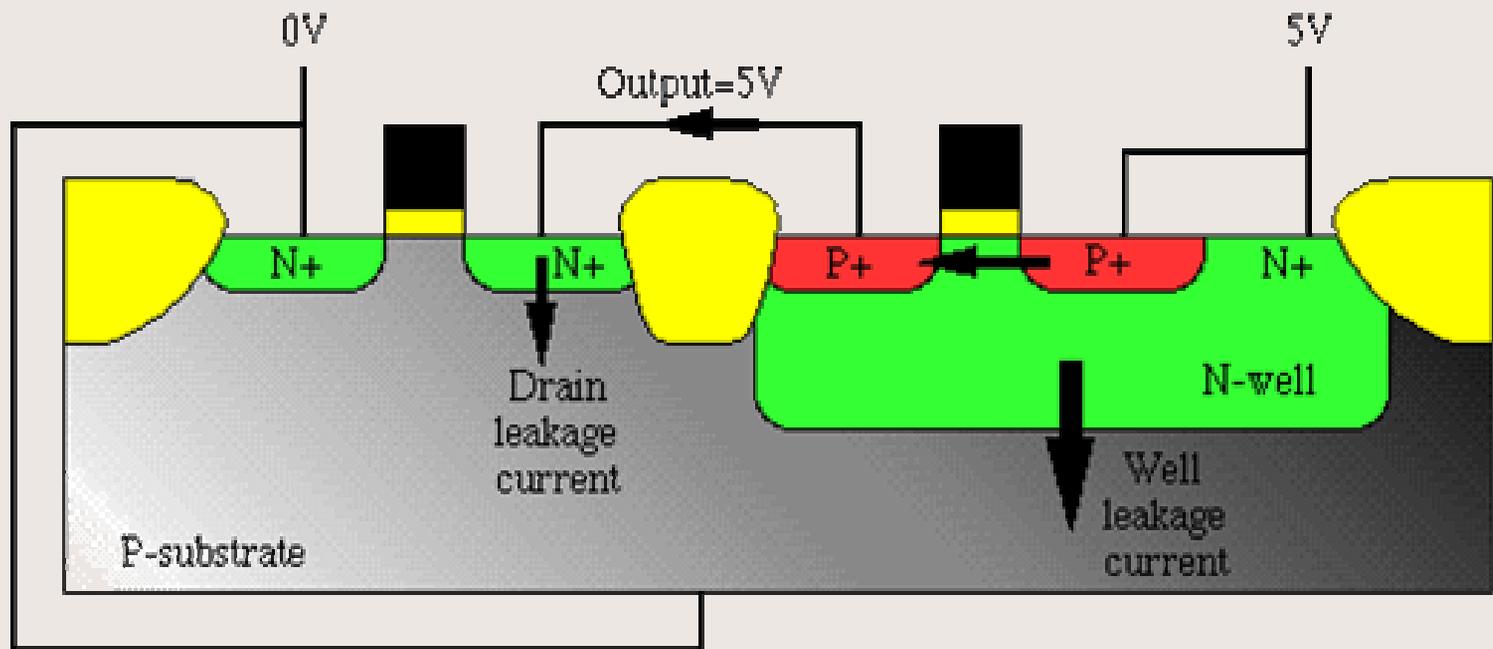
# Procesos CMOS

Procesos Bulk: substrato Si dopado	Silicio sobre aislante (SOI): substrato aislante (Zafiro)
Pozo p	
Pozo n	
Doble pozo	

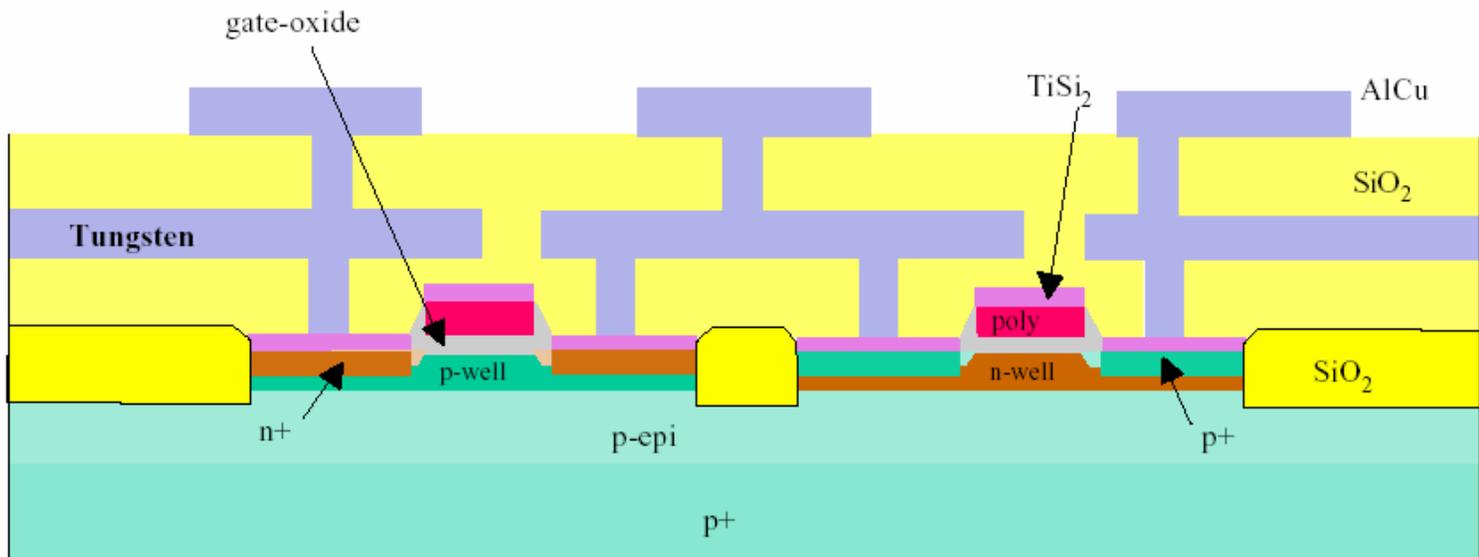
# Procesos CMOS: pozo p



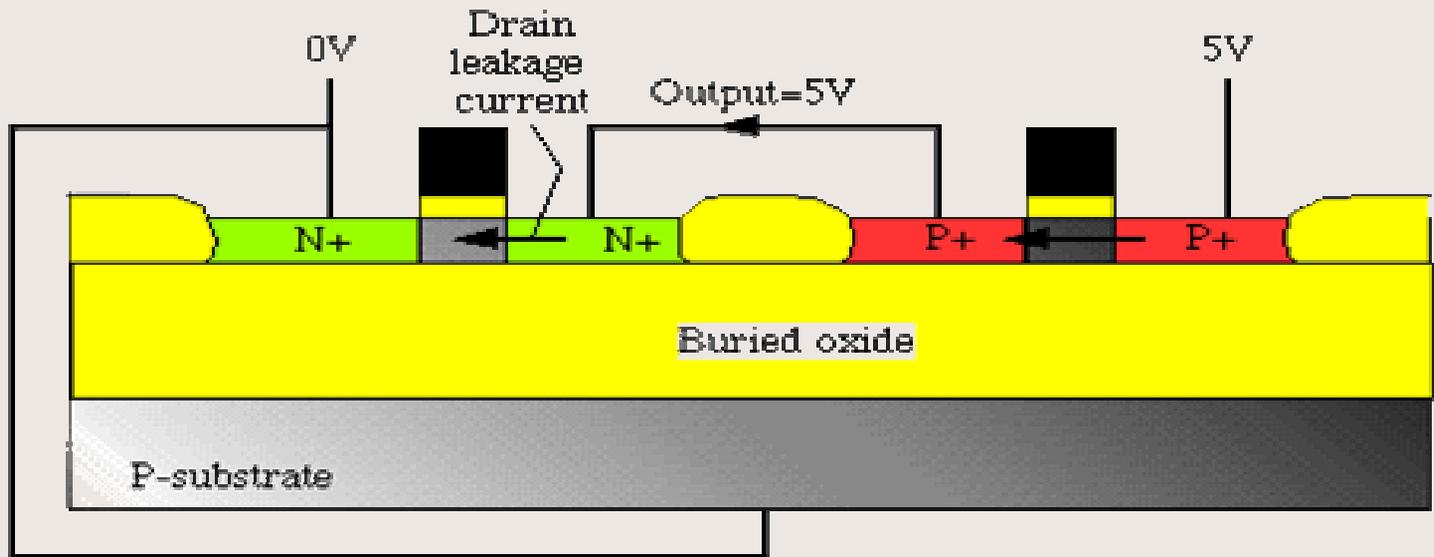
# Procesos CMOS: pozo n



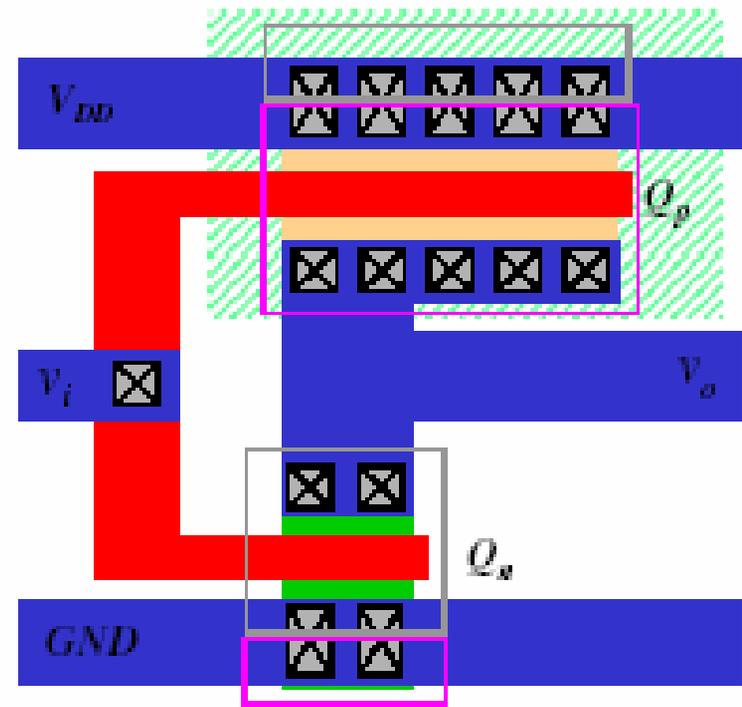
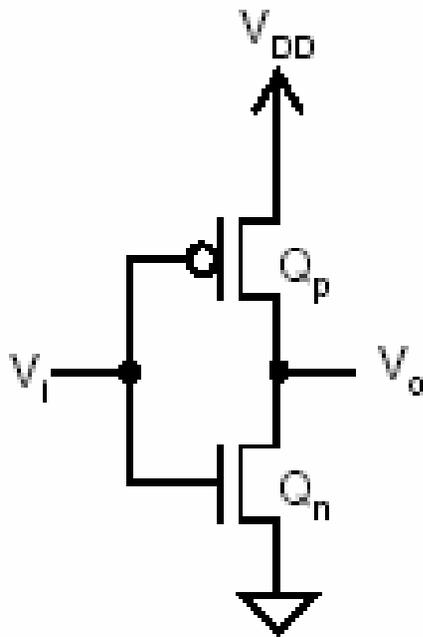
# Procesos CMOS: doble pozo



# Procesos CMOS: SOI

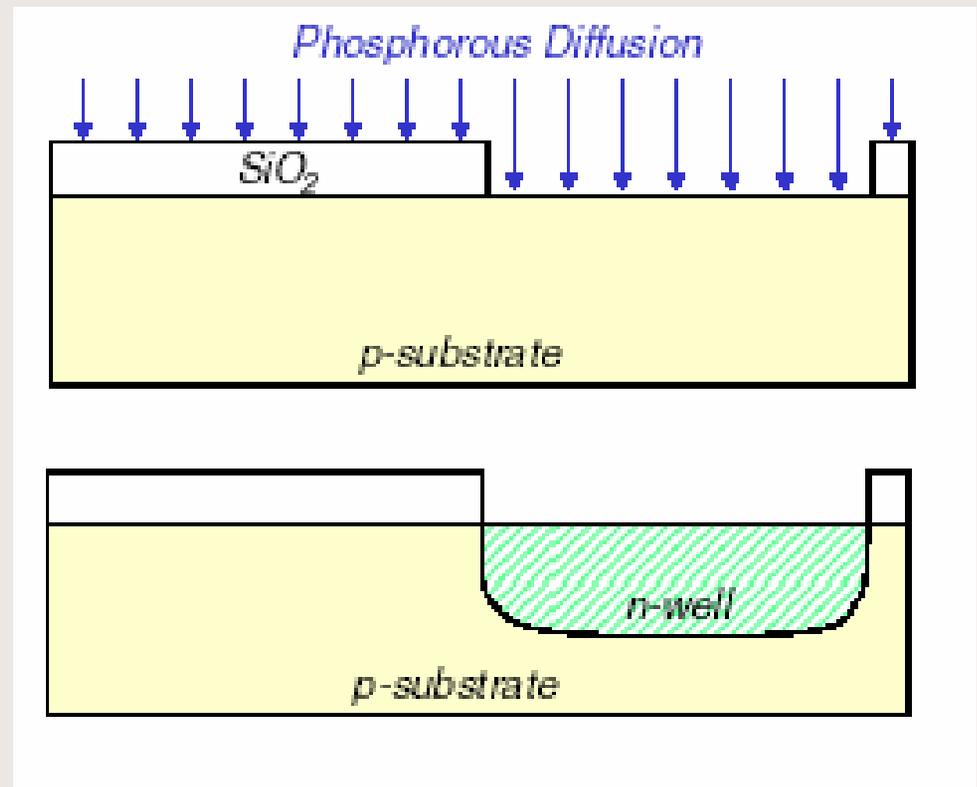
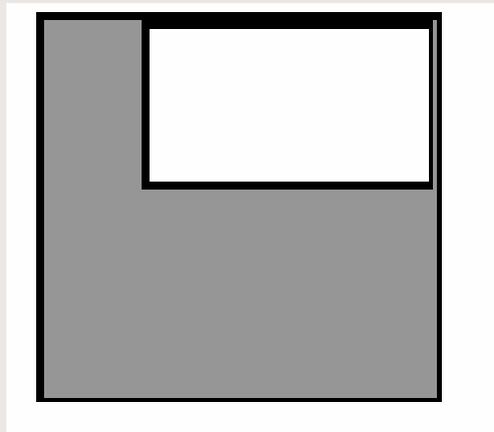


# Layout de un inversor

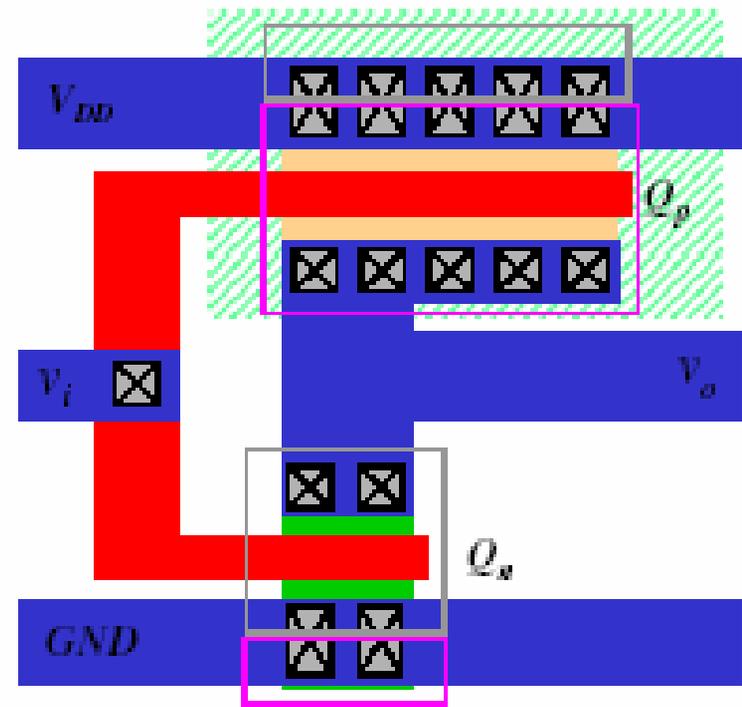
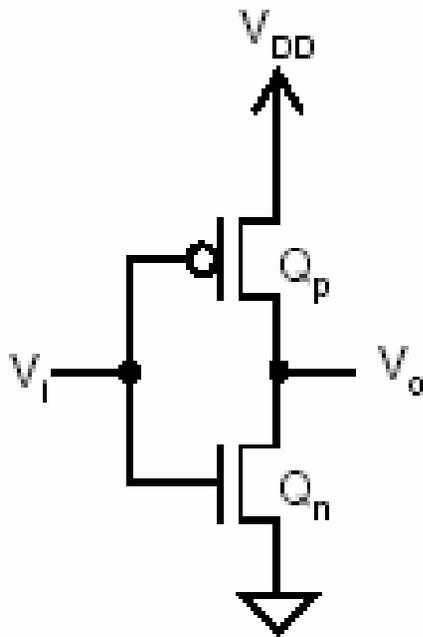


# Mascára 1: Difusión pozo n

Mascara para  
eliminar  
 $\text{SiO}_2$

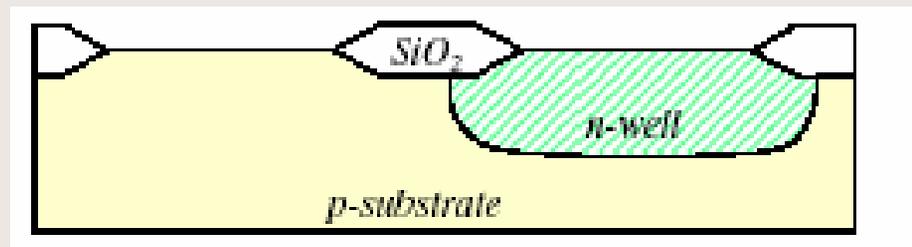
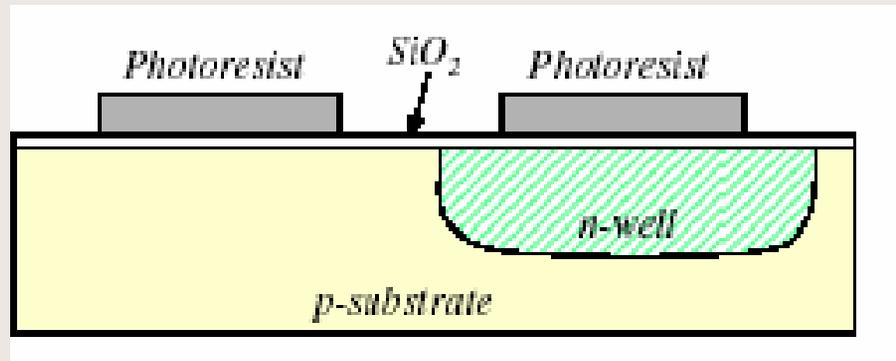
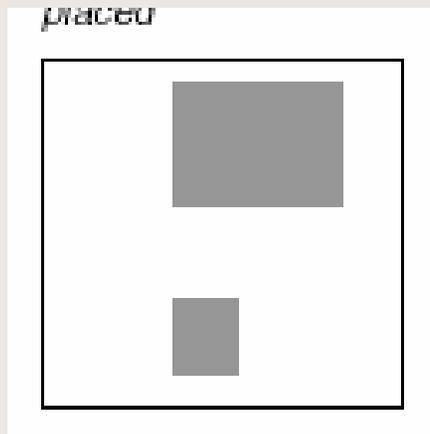


# Layout de un inversor

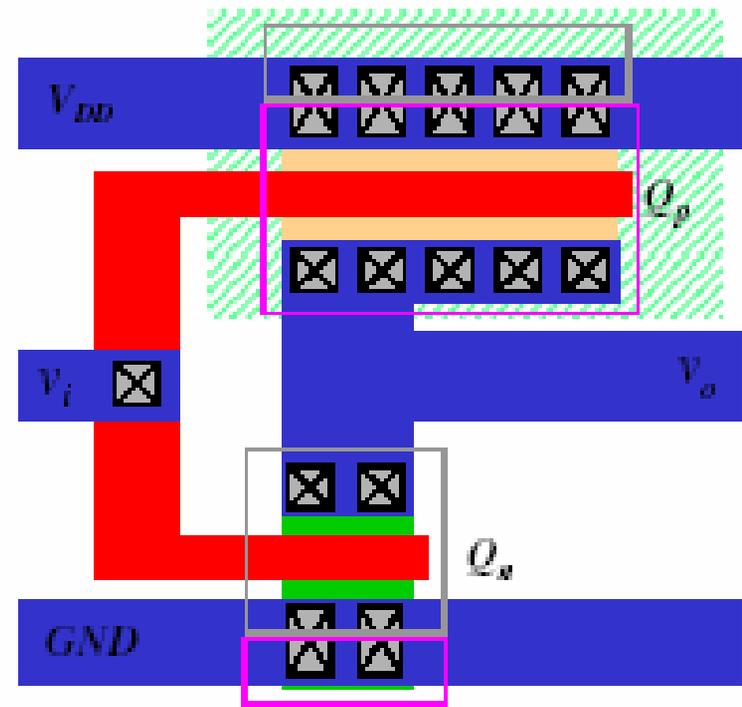
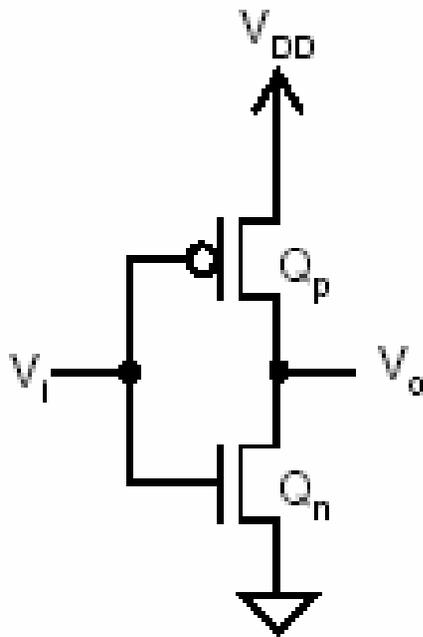


# Máscara 2: Definición de regiones activas

Define las regiones activas donde se van a colocar los dispositivos

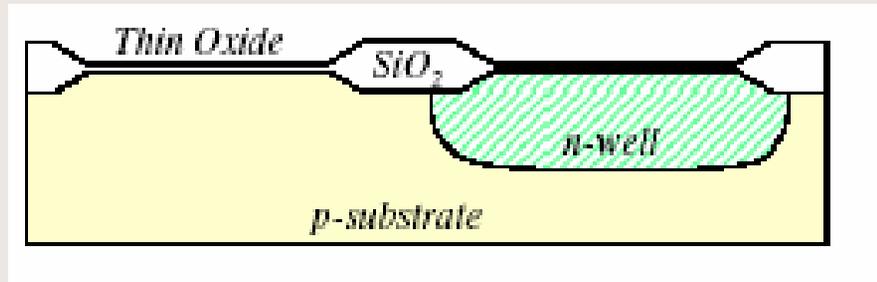
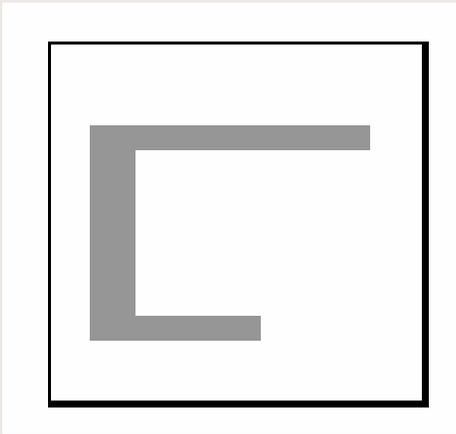


# Layout de un inversor

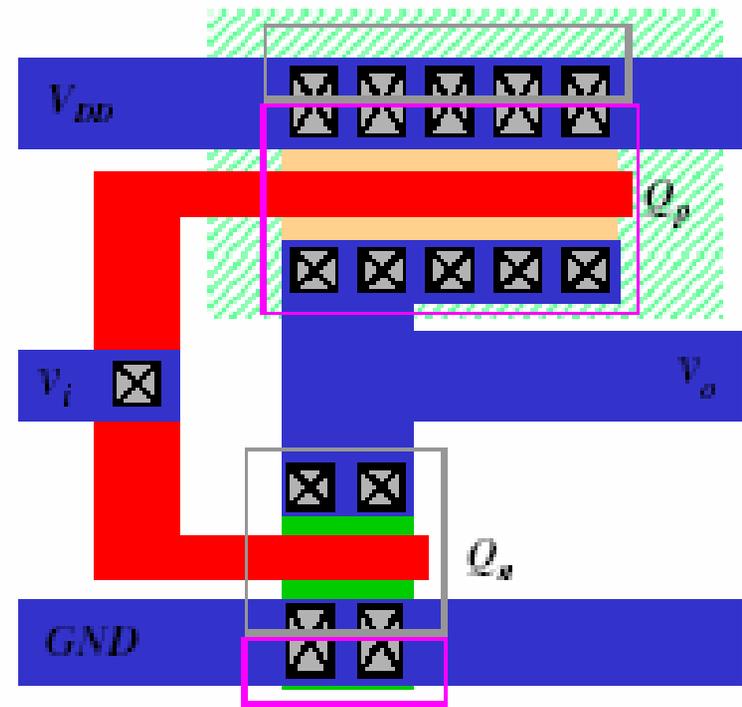
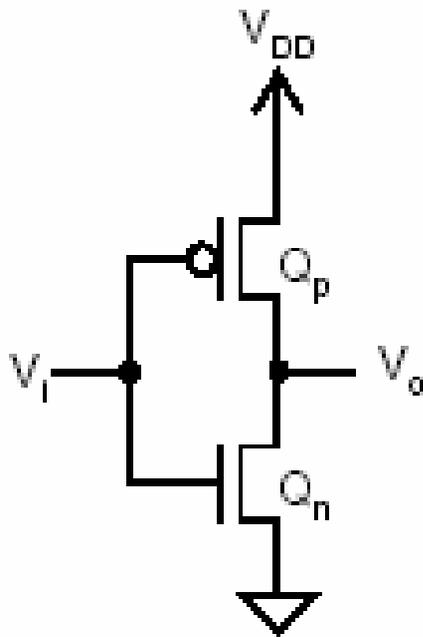


# Máscara 3: Puerta de polisilicio

Se deposita el polisilicio de puerta

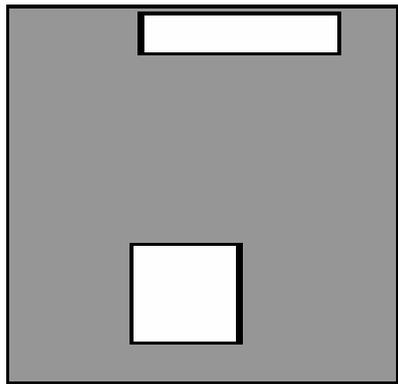
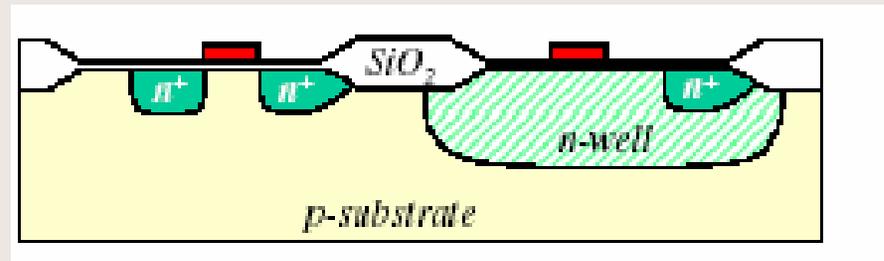
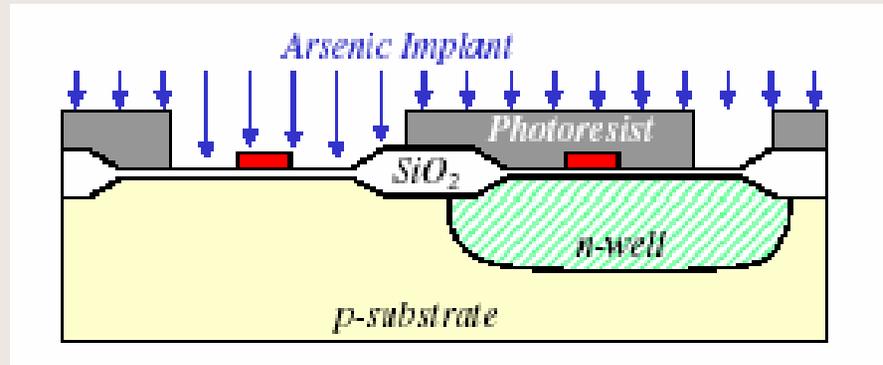


# Layout de un inversor

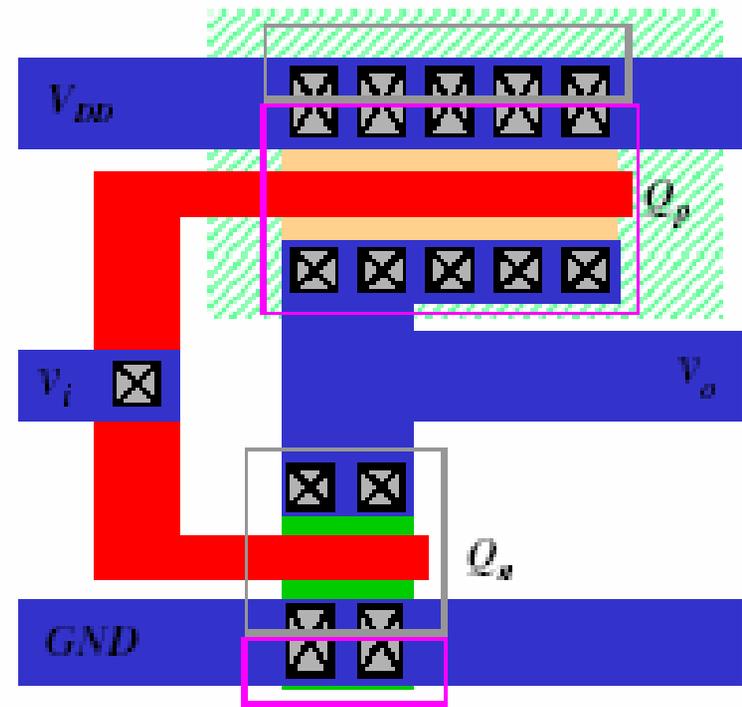
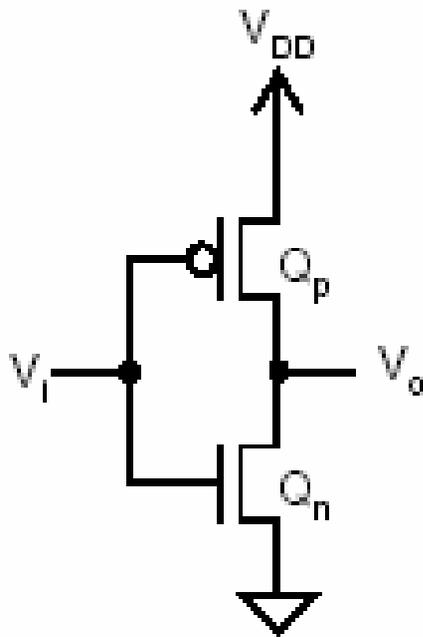


# Máscara 4: Difusión n+

Se crea la fuente y el drenador de los dispositivos n

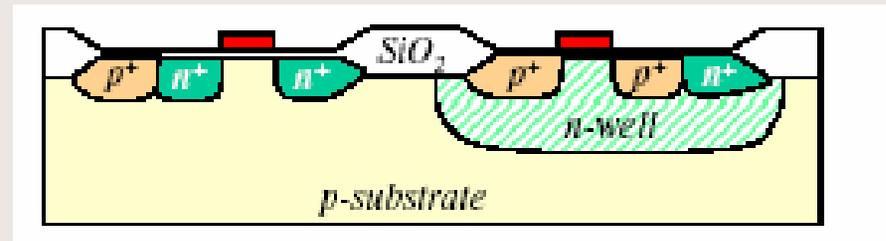
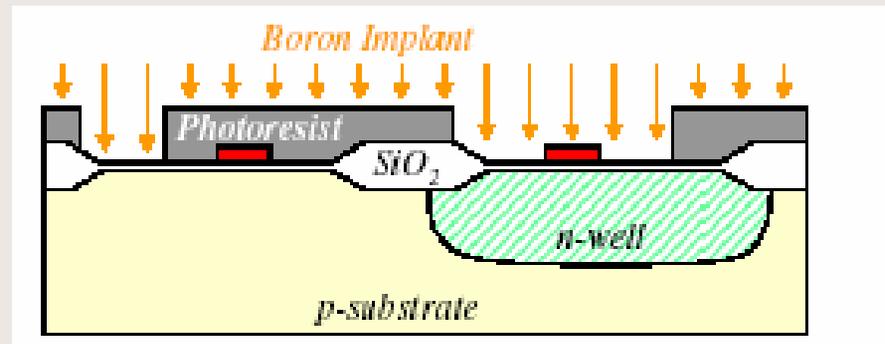
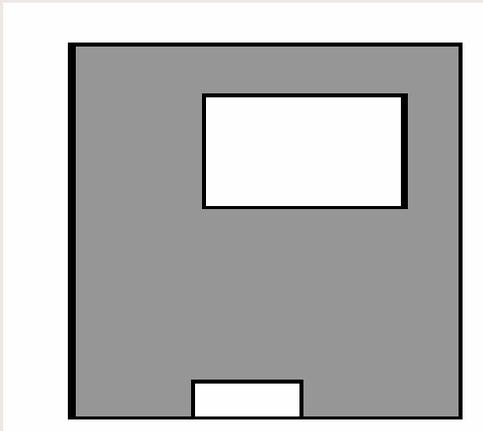


# Layout de un inversor



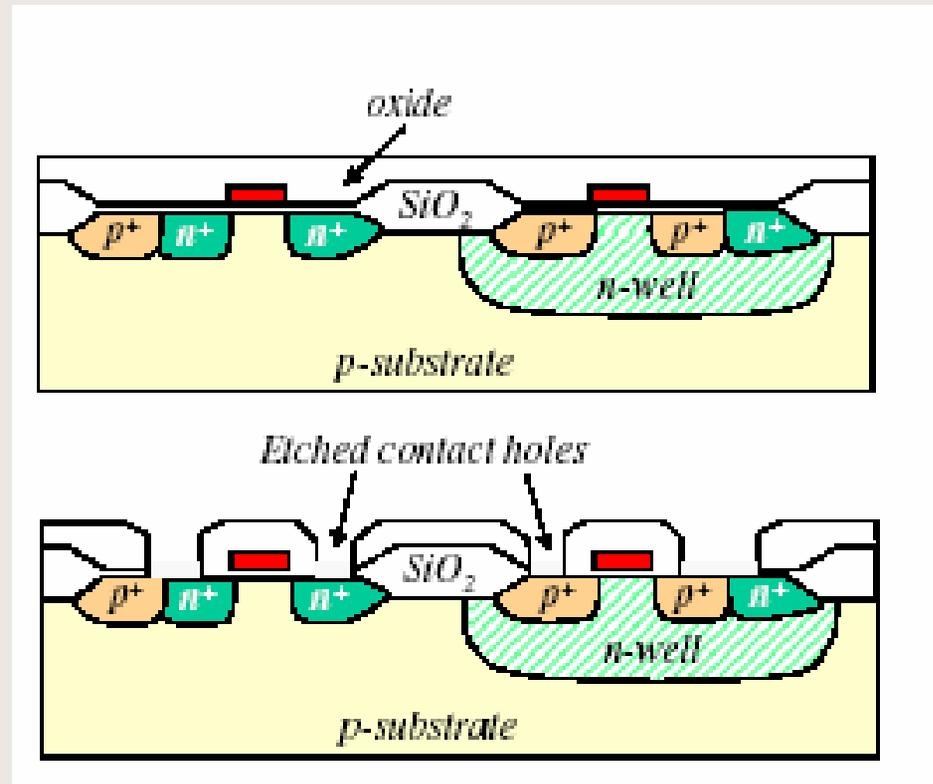
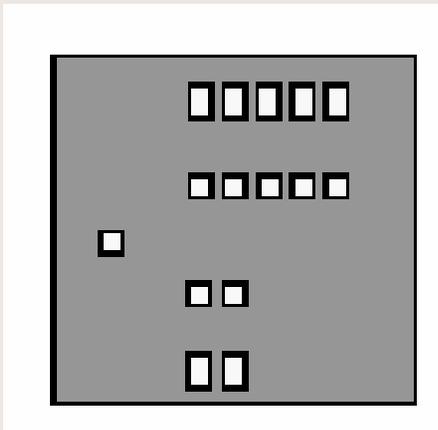
# Máscara 5: Difusión p+

Se crea la fuente y el drenador de los dispositivos p

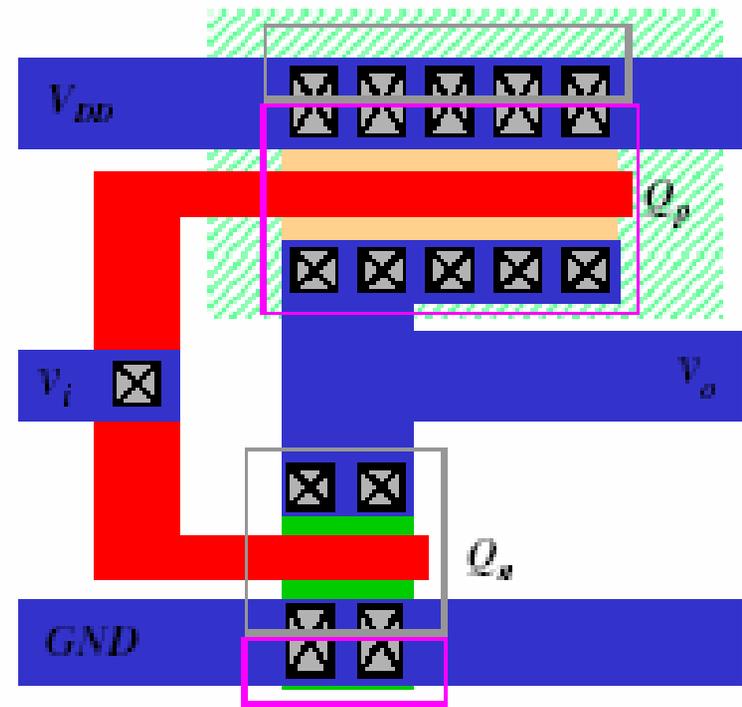
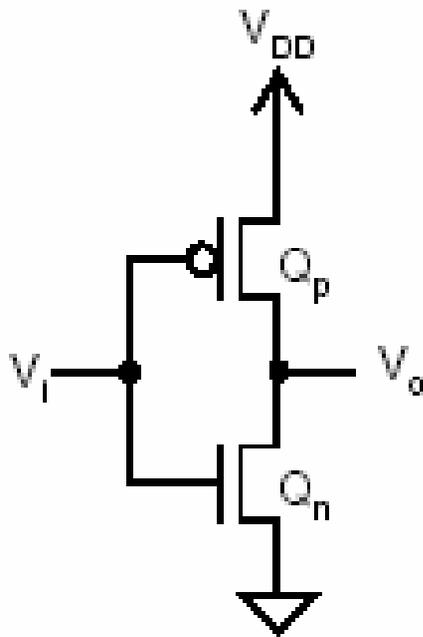


# Máscara 6: Agujeros de contactos

Determina las posiciones donde van los contactos

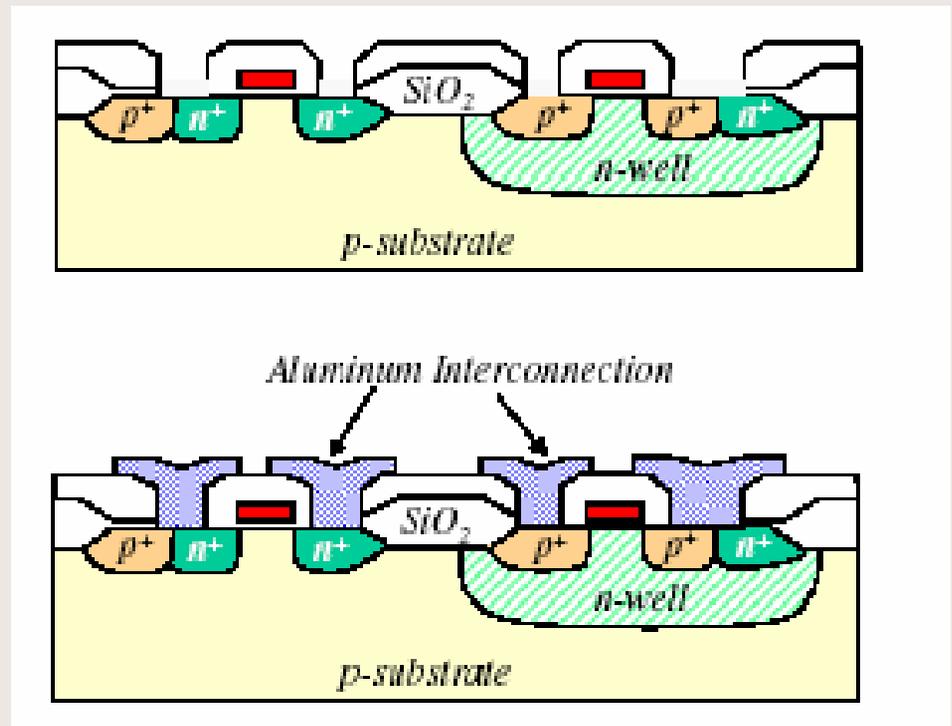
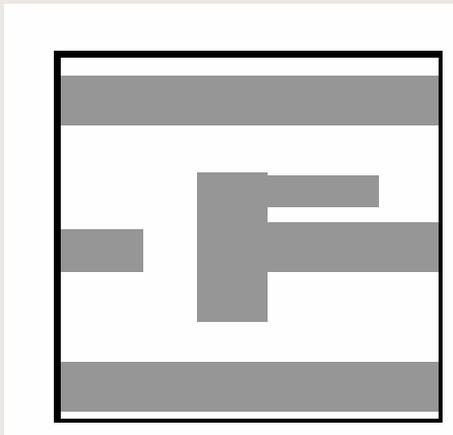


# Layout de un inversor

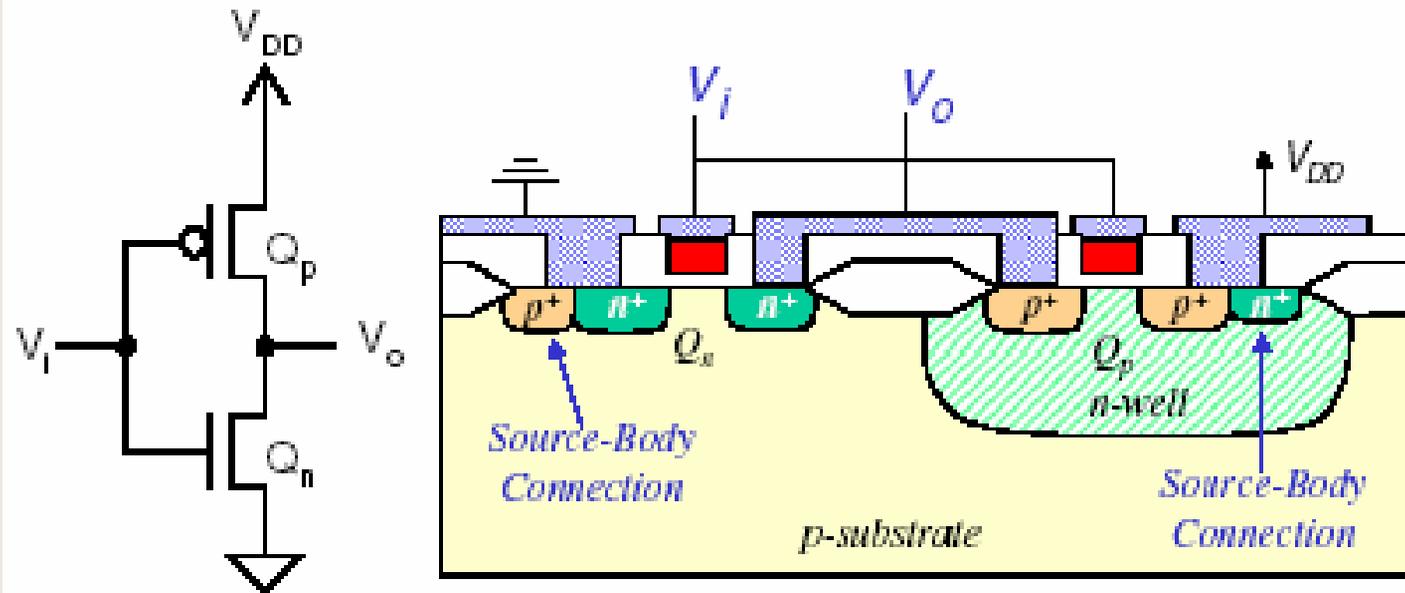


# Máscara 7: Metalización

Determina las posiciones donde van las interconexiones

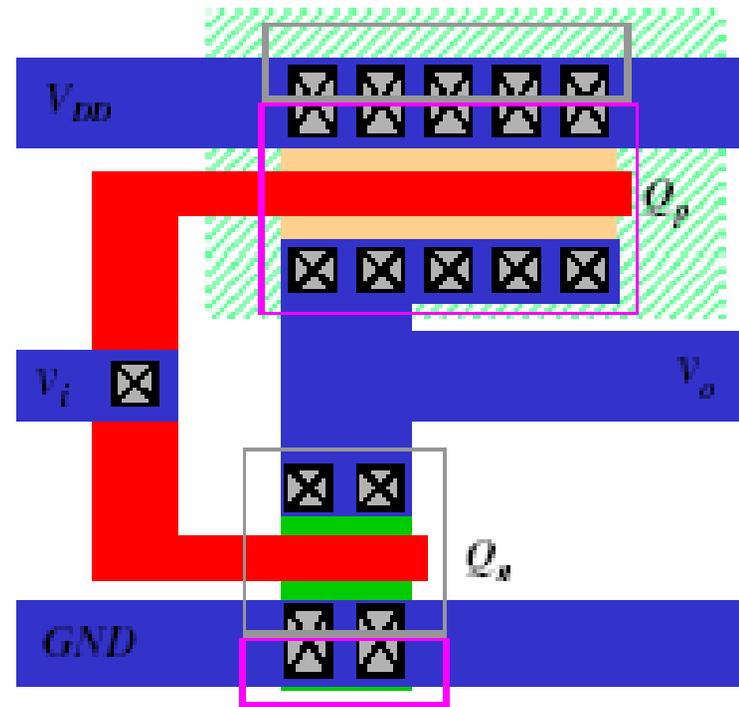


# Sección de un inverso CMOS



# Layout de un inverso CMOS

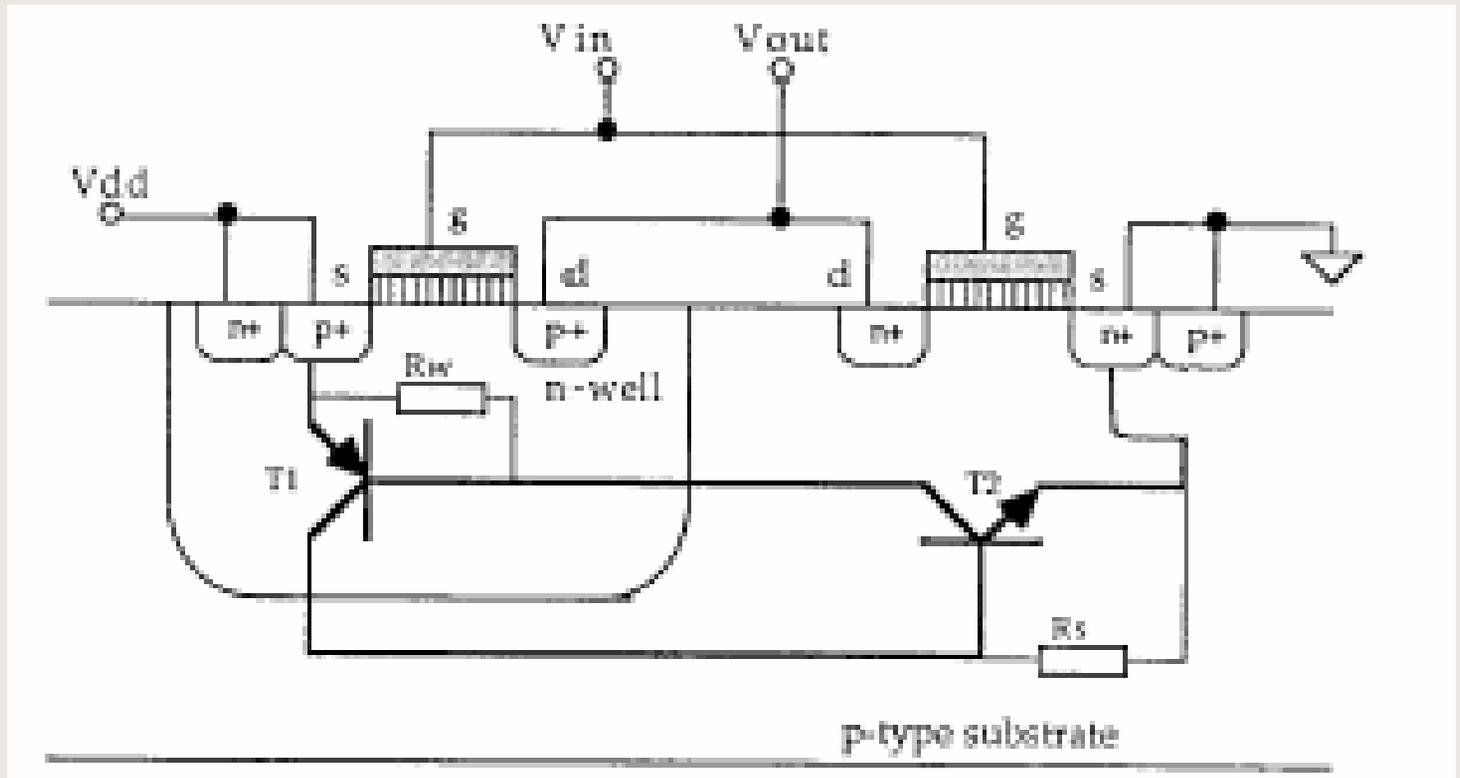
-  *n*-well
-  PMOS active region
-  NMOS active region
-  *n*<sup>+</sup> diffusion
-  *p*<sup>+</sup> diffusion
-  Poly 1 (poly-Si gate)
-  Contact Hole
-  Metal 1



# Efecto latch-up

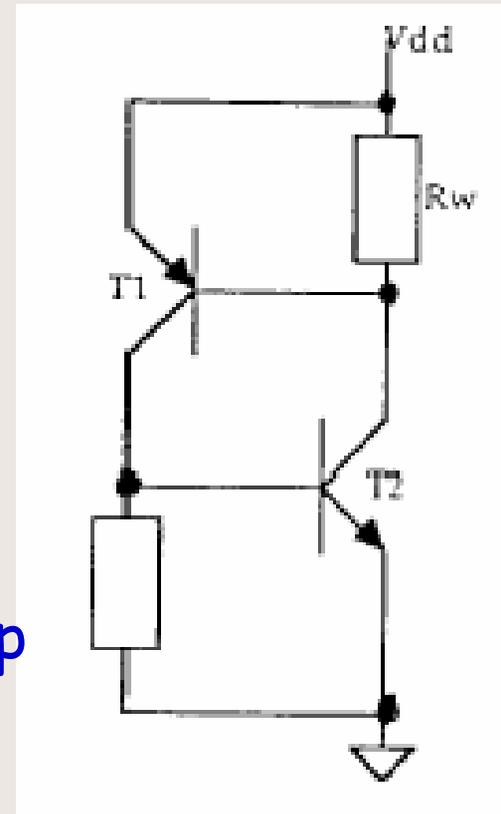
Definición: Generación de un camino de baja impedancia en CI CMOS entre alimentación y tierra debido a la aparición de transistores bipolares parásitos.

# Efecto latch-up



# Efecto latch-up

- T1 y T2 forman un circuito tristor
- Si  $R_w$  y/o  $R_s$  no 0 y T1 o T2 conducen, Vdd se cortocircuita con GND
- Los dos transistores conducen permanentemente hasta que se corta la alimentación → latch-up



# Reducción del efecto latch-up

- Reducción de la ganancia de los transistores parásitos
- Aumentando la distancia entre dispositivos de diferente tipo
- Anillos de guarda
- Contactos de pozo y substrato próximos a las fuentes de conexión

# Realización de un CI

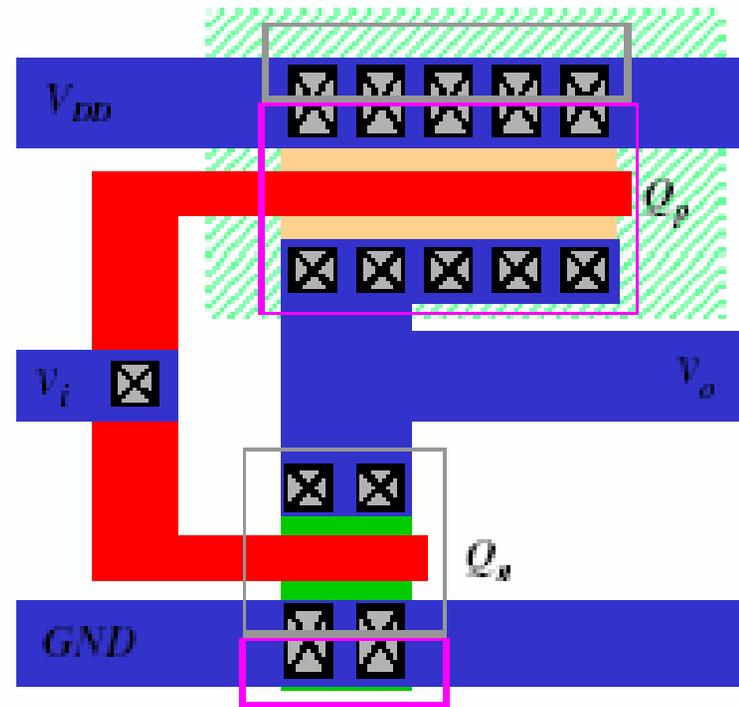
Proceso de diseño de un CI desde la concepción hasta la puesta en funcionamiento



(Caltech Interchange Format) Fichero C.I.F. ←

# Layout de un inverso CMOS

-  *n-well*
-  *PMOS active region*
-  *NMOS active region*
-  *n+ diffusion*
-  *p+ diffusion*
-  *Poly 1 (poly-Si gate)*
-  *Contact Hole*
-  *Metal 1*



- [http://bwrc.eecs.berkeley.edu/Classes/icdesign/ee141\\_s02/Lectures/Lecture5-Manufacturing.pdf](http://bwrc.eecs.berkeley.edu/Classes/icdesign/ee141_s02/Lectures/Lecture5-Manufacturing.pdf)
- <http://dunham.ee.washington.edu/ee539/notes/Chapter2.pdf>
- <http://tuttle.merc.iastate.edu/ee432/notes/mosprocessoverview/cmos70/cmos70.htm>

# Sección de un transistor

